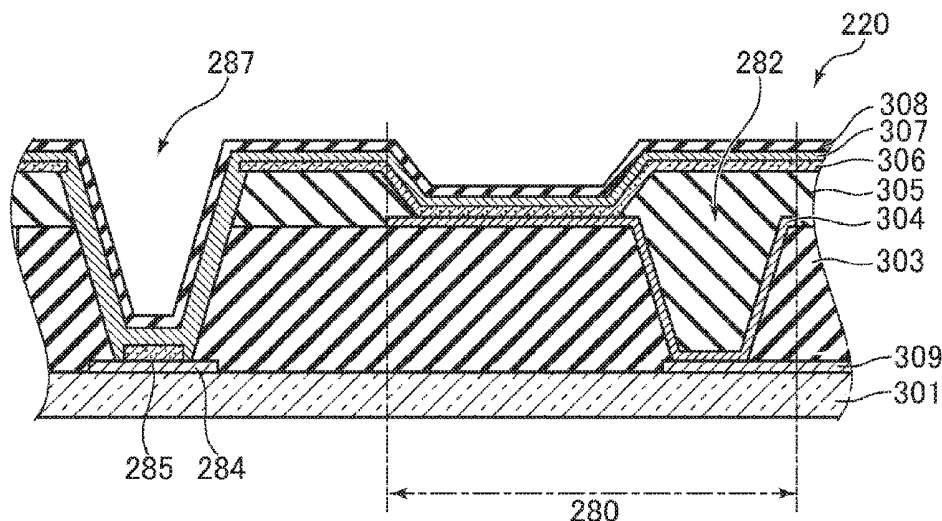


(10) **Patent No.:** US 10,608,070 B2
(45) **Date of Patent:** *Mar. 31, 2020



Related U.S. Application Data		7,960,908 B2 *	6/2011	Okutani		H01L 27/322	313/504
continuation of application No. 14/469,628, filed on Aug. 27, 2014, now Pat. No. 9,520,456.		8,053,983 B2 *	11/2011	Abe		H01L 51/5253	313/504
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(52) U.S. Cl.		2003/0201708 A1 *	10/2003	Yamada		H01L 27/1214	313/495
CPC <i>H01L 27/3262</i> (2013.01); <i>H01L 27/3279</i> (2013.01); <i>H01L 51/5203</i> (2013.01); <i>H01L 51/5234</i> (2013.01); <i>H01L 51/56</i> (2013.01)		2004/0056591 A1 *	3/2004	Koo		H01L 27/3244	313/506
(58) Field of Classification Search		2004/0160170 A1 *	8/2004	Sato		H01L 27/3276	313/504
CPC H01L 51/5253; H01L 51/5228; H01L 51/5212; H01L 27/3246; H01L 27/322; H01L 27/3211; H01L 2251/5315; Y10S 257/929		2005/0051776 A1 *	3/2005	Miyagi		G09G 3/3233	257/72
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		* cited by examiner					

FIG. 1

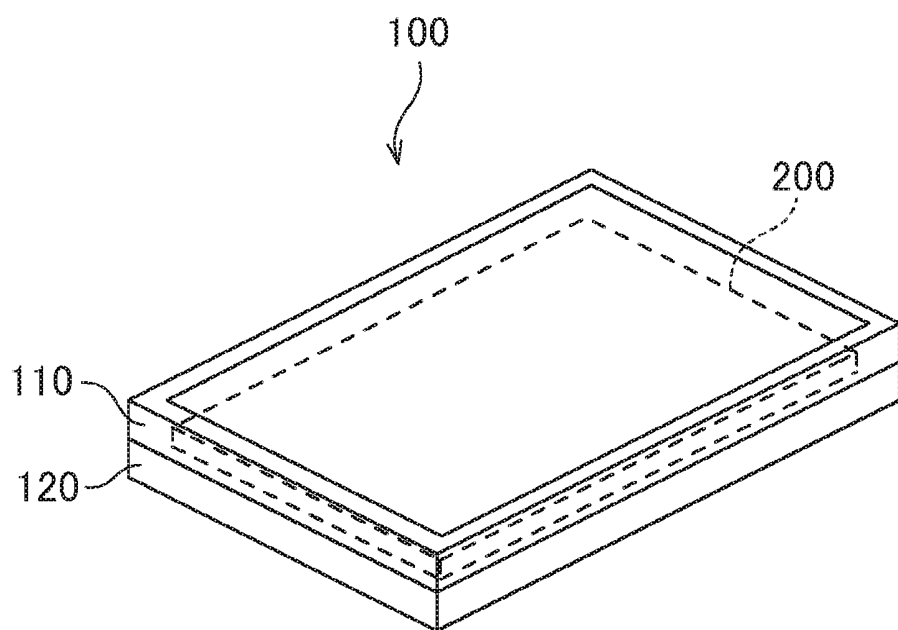


FIG. 2

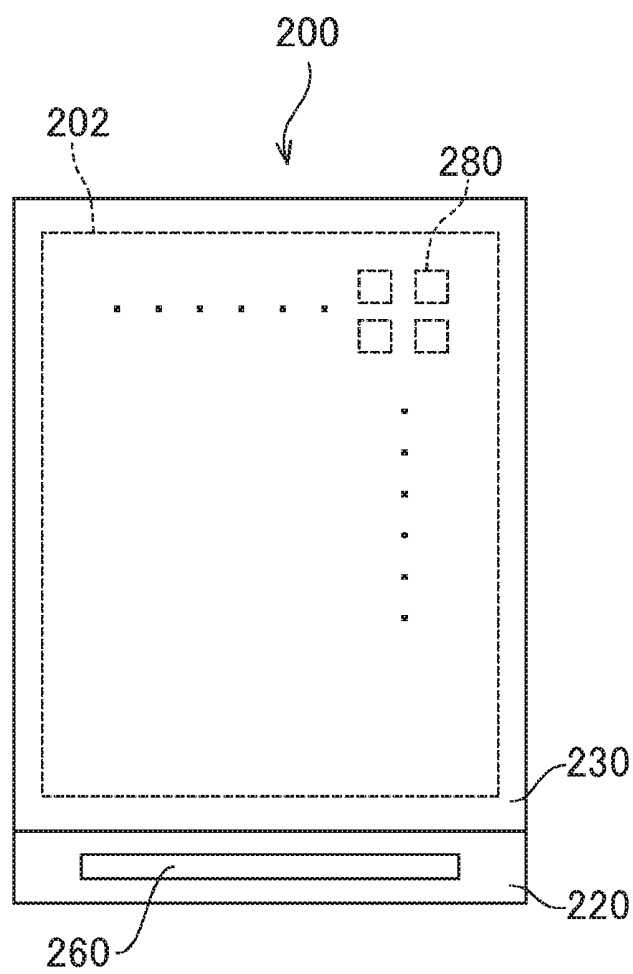


FIG.3

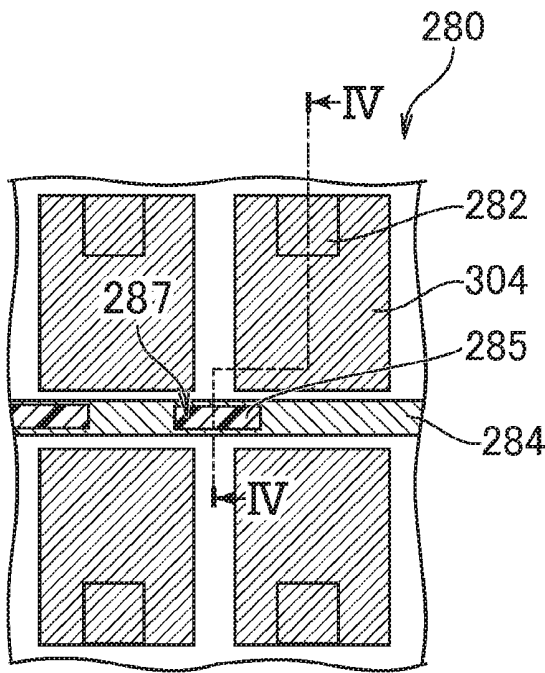
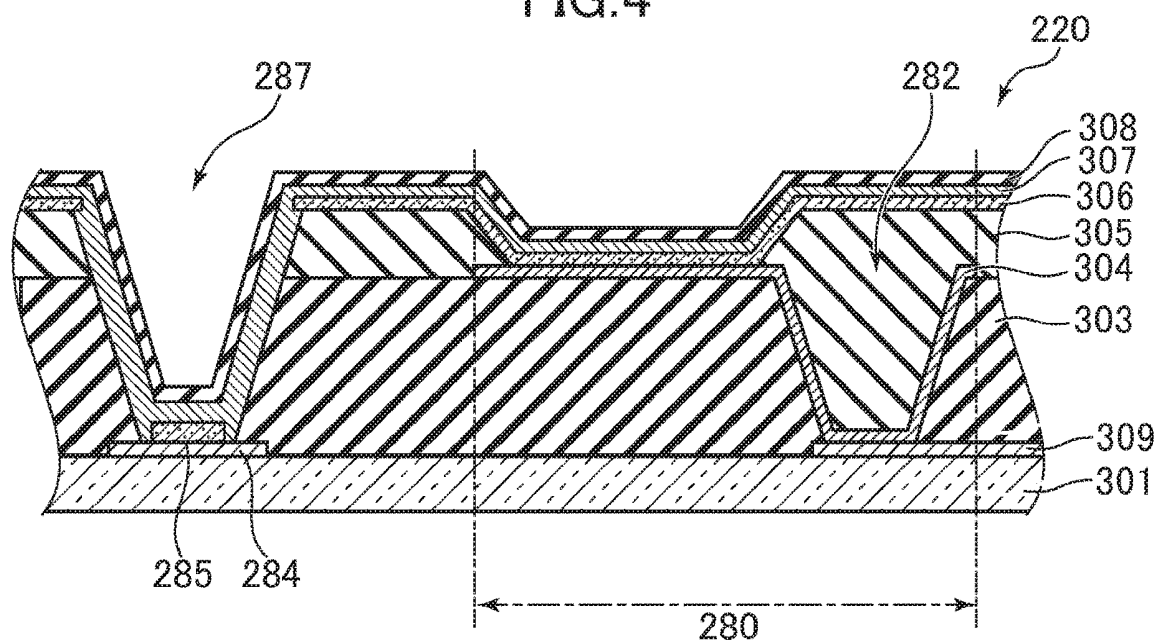


FIG. 4



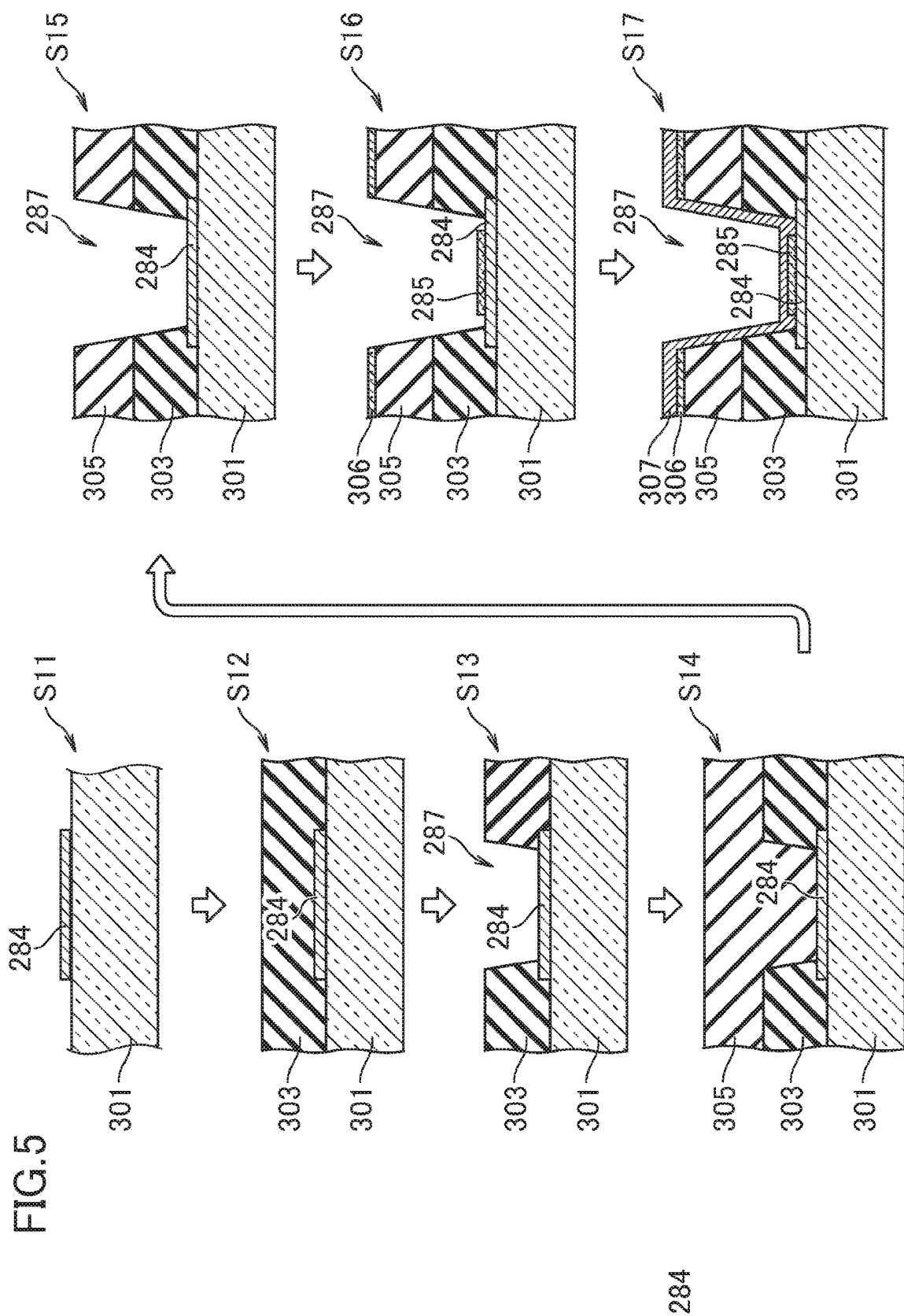
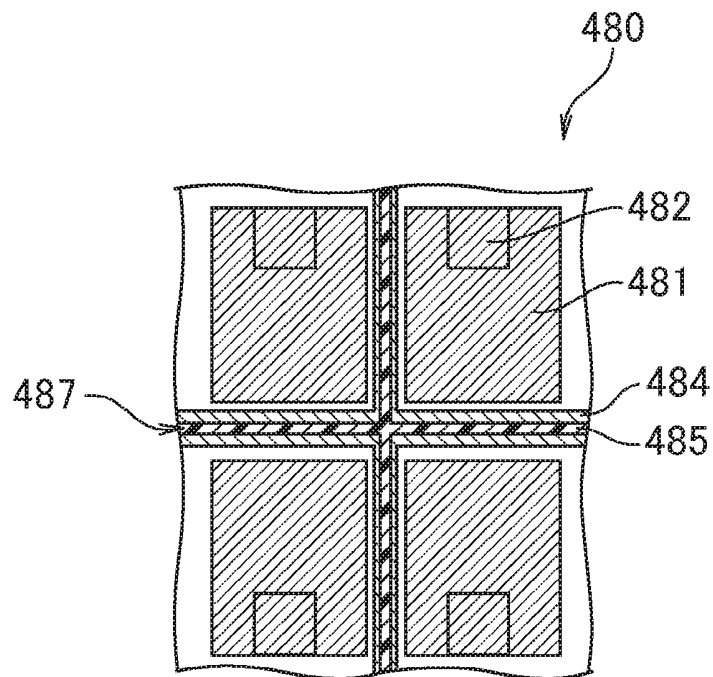


FIG. 6



ORGANIC EL DISPLAY DEVICE**CROSS-REFERENCE TO RELATED APPLICATIONS**

This application is a continuation of U.S. application Ser. No. 15/345,054 filed on Nov. 7, 2016 which, in turn, is a continuation of U.S. application Ser. No. 14/469,628, (now U.S. Pat. No. 9,520,456) filed on Aug. 27, 2014. Further, this application claims priority from Japanese application No. 2013-178680 filed on Aug. 29, 2013, the entire contents of which are hereby incorporated by reference into this application.

BACKGROUND OF THE INVENTION**1. Field of the Invention**

The present invention relates to an organic EL display device and a method of manufacturing the organic EL display device, and more specifically, to an organic EL display device that performs display by emitting light on a light emitting element which is a self-luminous body disposed in each pixel, and a method of manufacturing the same.

2. Description of the Related Art

In recent years, an image display device (hereinafter, referred to as "organic EL (Electro-luminescent) display device") using a self-luminous body called organic light emitting diode (OLED) is in practical use. Since the organic EL display device uses the self-luminous body, it is not only excellent in terms of visibility and response speed, but it is also possible to make the device thinner because an auxiliary illuminating device such as a backlight is not required, compared to a liquid crystal display in the related art.

In a display device in which light is emitted to a side on which a light emitting element of an insulated substrate is formed, that is, a top emission type display device, among an upper electrode and a lower electrode as two electrodes that sandwich an organic layer having at least a light emitting layer as a layer, the upper electrode is an electrode, which covers the entire surface of a display region on which the organic layer is formed, and is formed of a transparent conductive material. It is desired that the upper electrode be formed thinner in order to improve transmittance of light. However, the thinner the upper electrode is, the higher the resistance value is and the lower the voltage is. Therefore, luminance unevenness easily occurs at the end portion and the center of the display region.

JP 2004-207217 A discloses that an upper electrode is brought into contact with an auxiliary electrode in a layer which is the same as that of a lower electrode within a display region, through a connection hole and that the resistance of the upper electrode is reduced. JP 2011-221203 A discloses that an upper electrode is electrically connected to a conductive substrate through a connection hole within a display region.

SUMMARY OF THE INVENTION

Bringing the upper electrode into contact with the electrode of a metal having a high conductivity within the display region as disclosed in the above JP 2004-207217 A and JP 2011-221203 A is effective for reducing the resistance of the upper electrode and for uniformizing potential. How-

ever, in both cases, the connection hole is required for the organic layer. Therefore, in consideration of deposition precision of the organic layer formed using a deposition mask, it is difficult to open a highly precise hole and a connection hole which is opened in each pixel has a certain size. However, this reduces the area of a portion from which light is emitted, thereby resulting in degradation in a contrast of the display. Particularly, in an organic EL display device having an organic layer that covers the surface of a display region without using a deposition mask, it is difficult to provide the connection hole within the display region.

The invention has been made from the viewpoint of the above-described problems and an object of the invention is to provide an organic EL display device in which a potential of an upper electrode is uniformized without reducing the light emission area.

(1) An organic EL display device includes: a lower electrode which is disposed for every pixel disposed in a matrix shape within a display region and is formed of a conductive material, and in which a potential is controlled for every pixel; an upper electrode which is disposed so as to cover the display region and is formed of the conductive material; a first organic layer which is disposed between the lower electrode and the upper electrode and is formed of a plurality of layers including a light emitting layer formed of an organic material that emits light; a metal wire that extends between the pixels within the display region; and a second organic layer which is formed of a plurality of layers the same as that of the first organic layer and which comes into contact with a part of the metal wire and does not come into contact with the first organic layer. The upper electrode comes into contact with the metal wire in the periphery of the second organic layer.

(2) In (1), the organic EL display device may further include: a flattening film formed of the organic material covering a circuit which is formed on a substrate and includes the metal wire and a thin film transistor; and an insulating bank that covers an end portion of the lower electrode which is formed on the flattening film among the lower electrode, the first organic layer, and the upper electrode, and electrically insulates the pixels. The upper electrode may come into contact with the metal wire through a contact hole opened in the flattening film and the insulating bank.

(3) In (1) or (2), the upper electrode may continuously come into contact with the metal wire within the display region along the metal wire.

(4) In any one of (1) to (3), the metal wire may vertically and horizontally extend so as to surround each of the pixels within the display region.

(5) In any one of (1) to (4), the first organic layer may have the same light emitting layer in all of the pixels within the display region.

(6) A method of manufacturing an organic EL display device includes: a metal wire formation step of forming a metal wire between pixels in a display region in which the pixels are disposed in a matrix shape; an insulating wire formation step of forming an insulating film using an insulation material so as to cover the display region on the metal wire; a contact hole formation step of forming a contact hole through which at least a part of the metal wire is exposed with respect to the insulating film; an organic layer formation step of simultaneously forming a first organic layer which is disposed on the insulating film and is formed of a plurality of layers including a light emitting layer formed of an organic material that emits light, and a second organic layer which is disposed at the bottom of the

contact hole and is discontinuous to the first organic layer; and an upper electrode formation step of forming an upper electrode which is formed of a conductive material and which comes into contact with the metal wire and covers the display region, after the organic layer formation step.

(7) In (6), the method of manufacturing the organic EL display device may further include: a flattening film-formation step of forming a flattening film using the organic material on the metal wire after the metal wire formation step; a flattening film contact hole formation step of forming a contact hole through which the metal wire is exposed with respect to the flattening film; and a lower electrode formation step of forming a lower electrode for every pixels on the flattening film. The insulating film formed in the insulating film formation step may be an insulating bank that electrically insulates the pixels and the contact hole formation step may be an insulating bank contact hole formation step performed on the insulating bank.

(8) In (6) or (7), the organic layer formation step may be a step of forming an organic layer through a deposition method and the upper electrode formation step may be a step of forming the upper electrode through a sputtering method.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a view schematically showing an organic EL display device according to an embodiment of the invention.

FIG. 2 is a view showing a configuration of an organic EL panel of FIG. 1.

FIG. 3 is an enlarged view schematically showing four pixels of FIG. 2.

FIG. 4 is a cross-sectional view taken along line IV-IV of FIG. 3.

FIG. 5 is a view illustrating a step of forming an upper electrode which is formed in an upper electrode contact hole.

FIG. 6 is an enlarged view schematically showing four pixels of an organic EL display device as a modification example of the present embodiment.

DETAILED DESCRIPTION OF THE INVENTION

Hereinafter, an embodiment of the invention will be described with reference to the accompanying drawings. In the drawings, the same components will be denoted by the same reference numerals throughout and the detailed description thereof will be omitted.

FIG. 1 schematically shows an organic EL display device 100 according to the embodiment of the invention. As shown in FIG. 1, the organic EL display device 100 is formed of an organic EL panel 200 which is fixed so as to be interposed between an upper frame 110 and a lower frame 120.

FIG. 2 shows a configuration of the organic EL panel 200 of FIG. 1. The organic EL panel 200 has two substrates which are a thin film transistor (TFT) substrate 220 and a sealing substrate 230 and transparent resin (not shown) is filled between these substrates. The TFT substrate 220 has pixels 280 arranged in a display region 202 in a matrix shape. In addition, a driving IC (integrated circuit) 260 which is a driving circuit that applies a potential for electrically connecting a source and a drain with respect to a scanning signal line (not shown) of a pixel transistor, the scanning signal line being disposed in each pixel, and applies a voltage corresponding to a gradation value of a pixel with respect to a data signal line of each pixel transistor is mounted on the TFT substrate 220.

FIG. 3 is an enlarged view schematically showing four pixels 280 of FIG. 2. In FIG. 3, in order to describe the present embodiment, only a part of electrodes is shown by a solid line in a planar view regardless of the lamination relation. As shown in FIG. 3, each of the pixels 280 has an independent lower electrode 304 for every pixel 280, and an independent lower electrode contact hole 282 for every pixel 280 in which the lower electrode 304 is connected to source and drain electrodes 309 to be described later. As described below, a first organic layer 306 including a light emitting layer disposed on the entire surface of the display region 202, and an upper electrode 307 disposed on the first organic layer on the entire surface of the display region are disposed on the lower electrode 304 in this order. A metal wire 284 is disposed between the pixels 280 and a second organic layer 285 which has the same layer structure as that of the first organic layer 306 is mounted on the metal wire 284. An upper electrode contact hole 287 is formed such that the upper electrode 307 and the metal wire 284 are connected to each other.

FIG. 4 is a cross-sectional view taken along line IV-IV of FIG. 3. As shown in FIG. 4, the TFT substrate 220 has a glass substrate 301 which is an insulating substrate; the source and drain electrodes 309 and the metal wire 284 which are formed of a conductive material on the glass substrate 301; a flattening film 303 formed of an insulating material on the source and drain electrodes 309 and the metal wire 284; the lower electrode 304 connected to the source and drain electrodes 309 through a contact hole which is opened in the flattening film 303; an insulating bank 305 which covers an end portion of the lower electrode 304 and insulates between electrodes between pixels; a first organic layer 306 including a light emitting layer and a common layer such as an electron injection layer and a hole transport layer which are formed so as to substantially cover the entire display region 202 on the lower electrode 304 and the insulating bank 305; the upper electrode 307 which is formed so as to cover the entire display region 202 on the first organic layer 306; a sealing film 308 that blocks air or water in order to prevent the first organic layer 306 from deteriorating; and a second organic layer 285 formed on the metal wire 284. Although it is not shown in FIG. 4, the source and drain electrodes 309 are connected to the TFT, which is formed in each of the pixels 280, between the glass substrate 301 and the flattening film 303. The light emitting layer of the first organic layer emits light when a positive hole or an electron which is injected through the lower electrode 304 and an electron or a positive hole which is injected through the upper electrode 307 are recombined, an excited state is formed, and the state is transferred to a ground state.

As shown in FIG. 4, the upper electrode 307 comes into contact with the metal wire 284 disposed between the pixels 280 through the upper electrode contact hole 287. For this reason, the upper electrode 307 of which the resistance value is increased, by being thinly formed within the display region 202 can come into contact with the metal wire 284 having high conductivity within the display region 202. Therefore, the potential of the upper electrode 307 is uniformly maintained within the display region 202. The second organic layer 285 is disposed, on the metal wire 284 of a region formed with the upper electrode contact hole 287.

Here, the organic EL display device 100 according to the present embodiment is an organic EL display device with a system of emitting light with a uniform wavelength region (for example, W (white)) in the entire surface of the display region, and extracting light at a wavelength region corre-

sponding to RGB using a color filter provided in the sealing substrate **30**. However, the organic EL display device is not limited thereto and may be an organic EL display device with a system of emitting light at respective wavelength regions of RGB in the pixels, and extracting light without using the color filter. In this case, the first organic layer including the light emitting layer, and the second organic layer are formed by being painted in a dot shape or a stripe shape for every pixel through deposition or the like.

FIG. **5** is a view illustrating a step of forming the upper electrode **307** which is formed in the above-described upper electrode contact hole **287**. In the step, first, the metal wire **284** is formed in a metal wire formation step **S11**. Here, the metal wire **284** (not shown) can be simultaneously formed at the same step with any of a gate electrode, a drain electrode, and a source electrode of the TFT formed in each of the pixels, and other wires except for the TFT. In this case, the metal wire **284** may not only be directly formed on the glass substrate **301**, but may also be formed on an insulating film which is formed on the glass substrate **301**.

Next, in a flattening film-formation step **S12**, a flattening film **303** formed of an organic material such as a photosensitive organic material is formed. In a flattening film-contact hole formation step **S13**, the upper electrode contact hole **287** is formed on the flattening film **303** through a well-known photolithography step to expose the metal wire **284**. Then, although it is not shown in FIG. **5**, in a lower electrode formation step, the lower electrode **304** is formed within the pixel **280**. In an insulating bank-format ion step **S14**, an end portion of the lower electrode **304** is covered and an insulating bank **305** which insulates the pixels and is formed of an organic material or an inorganic material is formed. Subsequently, in an insulating bank-contact hole formation step **S15**, the upper electrode contact hole **287** is formed in the insulating bank **305** through the well known photolithography step to expose the metal wire **284**.

The flattening film **303** can be formed by covering the entire TFT circuit formed on the glass substrate **301** and the upper electrode contact hole **287** of the flattening film **303** can be simultaneously formed in the same step as that of forming the lower electrode contact hole **282** of FIG. **4**. In addition, the upper electrode contact hole **287** of the insulating bank **305** can be simultaneously formed with the step of exposing the lower electrode **304** from the insulating bank **305**.

In an organic layer formation step **S16**, the first organic layer **306** and the second organic layer **285** are simultaneously formed through deposition. Here, the first organic layer **306** and the second organic layer **285** are simultaneously formed through the deposition. However, an organic material which is heated in a vacuum is adhered thereto with directivity. Therefore, the first organic layer **306** which is formed on the insulating bank **305** and the second organic layer **285** which is formed on the metal wire **284** are formed as discontinuous layers (stepping structure) by an extremely large step in the upper electrode contact hole **287**. The first organic layer **306** and the second organic layer **285** in the present embodiment are set to be formed through the deposition, but can be formed by a formation method such as offset printing so as to make discontinuous layers by providing a step.

Lastly, in an upper electrode formation step **S17**, the upper electrode **307** is formed through a sputtering method using a transparent electrode such as indium tin oxide (ITO) and indium zinc oxide (InZnO). The transparent electrode formed through the sputtering method has good throwing power compared to the deposition of the organic material.

Therefore, the transparent electrode is adhered even to the discontinuous portion between the first organic layer **306** and the second organic layer **285** and is formed as a continuous upper electrode **307** coming into contact with the metal wire **284**.

In a subsequent step, a sealing film is formed using SiN or a glass cap which is a well-known step. Therefore, the detailed description thereof will be omitted. In the present embodiment, the upper electrode contact hole **287** is set to be formed in both of the flattening film **303** and the insulating bank **305**. However, the metal wire may be formed on the flattening film **303** and the upper electrode contact hole **287** may be formed only in the insulating bank **305**, for example.

As described above, in the present embodiment, the upper electrode **307** can be brought into contact with the metal wire **284** having a low resistance value on the glass substrate **301** in the display region **202**. Therefore, it is possible to reduce the sheet resistance of the upper electrode **307** and save the power consumption. In addition, partial voltage reduction does not occur in the display region **202**, and therefore, it is possible to maintain uniformity of display. Furthermore, it is possible to bring the upper electrode **307** into contact with the metal wire **284** without patterning the first organic layer and the second organic layer. Therefore, it is possible to maintain the area of the light emitting region of the pixel to be large and to make the pixel a high definition pixel without increasing the number of steps. Particularly, it is possible to effectively apply the principle to an organic EL display device which has an organic layer including a light emitting layer formed on the entire surface of a display region **202** or a common layer. However, it is possible to apply the principle even to an organic EL display device formed of light emitting layers mutually having different wavelength regions of emitted light.

FIG. **6** is an enlarged view schematically showing four pixels **480** of an organic EL display device as a modification example of the present embodiment. Similarly to FIG. **3**, in order to describe the present embodiment, only a part of electrodes is shown by a solid line in a planar view regardless of the lamination relation. Similarly to the above-described embodiment, each of pixels **480** has a lower electrode **481** and a lower electrode contact hole **482**. Points different from the above-described embodiment is that a metal wire **484** which is connected to an upper electrode **407** is vertically and horizontally disposed between the pixels **480**, and an upper electrode contact hole **487** and a second organic layer **485** which is formed on the upper electrode contact hole **487** are also vertically and horizontally disposed along the metal wire **484**. Even in this case, in order to ensure the opening ratio, it is desirable that the area of the upper electrode contact hole **487** be smaller than or equal to 10% of the area of the lower electrode **481**.

With such a configuration, the first organic layer becomes an independent discontinuous layer (stepping structure) for every pixel **480**, and therefore, it is possible to suppress light emission at adjacent pixels, that is, electrical color mixture caused by leakage of a current to the adjacent pixels, in addition to obtaining the effect in the above-described embodiment. Moreover, the organic bank also becomes discontinuous for every pixel **480**, and therefore, the leaked light entering the organic bank by being emitted in a horizontal direction is not emitted from the adjacent pixels if the leaked light does not pass the interface of many layers. Thus, it is also possible to suppress optical color mixture.

In the present embodiment, the organic EL display device in which the same kinds of organic layers are formed on the

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entire display region is described. However, the organic EL display device in which organic layers are formed for every pixel having different wave regions of emitted light may also be used.

Various modification examples and correction examples can be conceived by those skilled in the art in the category of the idea of the invention. Accordingly, it is understood that the modification examples and the correction examples also belong to the scope of the invention as long as they have the gist of the invention.

What is claimed is:

1. An organic EL display device comprising:

a first lower electrode in a display region;

a second lower electrode in the display region;

an upper electrode covering the display region;

a wire running between the first lower electrode and the second lower electrode;

a contact hole on the wire; and

an organic layer between the upper electrode and the first lower electrode, or between the upper electrode and the second lower electrode, the organic layer including at

least one layer of an electron injection layer, a hole transport layer and a light emitting layer, wherein

the organic layer includes a first part which is in contact with the first lower electrode, a second part which is in contact with the second lower electrode, and a third part which is in contact with a part of the wire within the contact hole,

the third part of the organic layer is between the first part of the organic layer and the second part of the organic layer,

the first part of the organic layer and the third part of the organic layer are separated at an edge of the contact hole,

the second part of the organic layer and the third part of the organic layer are separated at another edge of the contact hole, and

the upper electrode is in contact with another part of the wire within the contact hole.

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2. The organic EL display device according to claim 1, further comprising:

a flattening film formed of organic material covering a circuit which is formed on a substrate and includes the wire and a thin film transistor; and

an insulating bank covering an end portion of the first lower electrode and an end portion of the second lower electrode, the insulating bank formed on the flattening film among the first lower electrode, the second lower electrode, the organic layer, and the upper electrode, wherein

the insulating bank isolates each of the first lower electrode and the second lower electrode,

the upper electrode is in contact with the wire through the contact hole opened in the flattening film and the insulating bank.

3. The organic EL display device according to claim 1, wherein

the upper electrode continuously is in contact with the wire within the display region along the wire.

4. The organic EL display device according to claim 1, wherein

the wire runs along a plurality of sides of the first lower electrode and the second lower electrode.

5. The organic EL display device according to claim 4, wherein

the contact hole is formed along a plurality of sides of the first lower electrode and the second lower electrode.

6. The organic EL display device according to claim 4, wherein

the wire vertically and horizontally runs so as to surround each of the first lower electrode and the second lower electrode.

7. The organic EL display device according to claim 6, wherein

the contact hole is formed vertically and horizontally so as to surround each of the first lower electrode and the second lower electrode.

* * * * *

专利名称(译)	有机EL显示装置		
公开(公告)号	US10608070	公开(公告)日	2020-03-31
申请号	US16/135102	申请日	2018-09-19
[标]申请(专利权)人(译)	株式会社日本显示器		
申请(专利权)人(译)	日本展示INC.		
当前申请(专利权)人(译)	日本展示INC.		
[标]发明人	MATSUMOTO YUKO SATO TOSHIHIRO		
发明人	MATSUMOTO, YUKO SATO, TOSHIHIRO		
IPC分类号	H01L51/52 H01L51/50 H01L27/28 H01L27/32 H01L51/56		
CPC分类号	H01L27/3246 H01L27/3248 H01L27/3262 H01L27/3276 H01L51/56 H01L27/3279 H01L51/5203 H01L51/5234		
优先权	2013178680 2013-08-29 JP		
其他公开文献	US20190019857A1		
外部链接	Espacenet		

摘要(译)

有机EL显示装置具备：下部电极；以及下部电极。上电极；第一有机层，其设置在下部电极和上部电极之间并且由包括发光层的多个层形成，该发光层由发光的有机材料形成；在显示区域内的像素之间延伸的金属线；第二有机层，该第二有机层由与第一有机层相同的多层形成，并且与金属线的一部分接触并且不与第一有机层接触。上电极在第二有机层的外围与金属线接触。因此，可以在不减小发光面积的情况下使上部电极的电位均匀。

